



FSC-HC05

Bluetooth V3.0 Module Datasheet

Version 1.0

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Revision History

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1. INTRODUCTION

Overview

FSC-HC05 is a high-performance, highly integrated Bluetooth BR/EDR module, designed to operate on the 2400MHz to 2480 MHz ISM frequency band.

Abundant peripherals, power-on reset (POR) and I2C/USB, arithmetic accelerators further reduce the cost and size of the entire system.

By default, Feasycom standard firmware is built-in, and customized firmware is also available. FSC-HC05 is a suitable product for designers who want to add wireless functions to their products.

Features

- BR/EDR Proprietary RF SOC
- UART programming and data interface (baud rate can up to 921600bps)
- I2C/USB interfaces
- Digital Peripherals
 - Two-wire Master (I2C compatible) , up to 400kbps
 - LED drive capability
 - AES256 HW encryption
 - USB2.0 full speed , support host mode
- Dual Core Digital Architecture
 - ARM Cortex-M0 Core for application
 - 32bit-Risc Core for link management
- 2.4GHz Transceiver
 - Single-end RFIO
 - Receive Sensitivity : -95dBm
 - Tx Power 5dBm(Maximum)
- Postage stamp sized form factor
- Working current is 5mA
- Support External Antenna

- RoHS compliant

Application

- Health Thermometer
- Heart Rate
- Blood Pressure
- Proximity

Module picture as below showing

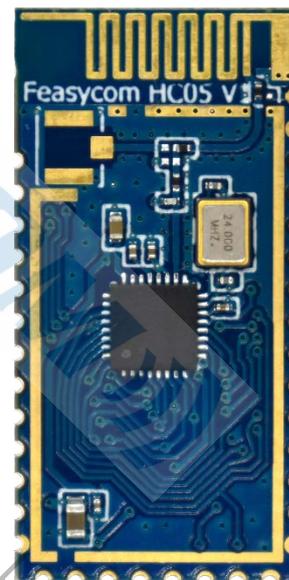


Figure 1: FSC-HC05 Picture

2. General Specification

Table 1: General Specifications

Categories	Features	Implementation
Wireless Specification	Bluetooth Version	Bluetooth V3.0
	Frequency	2.400 - 2.480 GHz
	Transmit Power	5dBm (Maximum)
	Receive Sensitivity	-95 dBm @0.1% (BR/EDR mode)
	Modulation	GFSK
Host Interface and Peripherals	UART Interface	TX, RX, Supports Automatic Flow Control (CTS and RTS lines).
		General Purpose I/O Default 115200,N,8,1
	GPIO	Baudrate support from 1200 to 921600
		5, 6, 7, 8 data bit character
		16 (maximum – configurable) lines
I2C Interface	1 (configurable from GPIO total). Up to 400 kbps	
Profiles	Classic Bluetooth	SPP
FW upgrade		OTA, ICE
Supply Voltage	Supply	3.3V ~ 3.6V
Power Consumption		Working current 5mA
Physical	Dimensions	13mm X 26.9mm X 2.0mm; Pad Pitch 1.5mm
Environmental	Operating	-20°C to +85°C
	Storage	-20°C to +85°C
Miscellaneous	Lead Free	Lead-free and RoHS compliant
	Warranty	One Year
Humidity		10% ~ 90% non-condensing
MSL grade:		MSL 3
ESD grade:		Human Body Model: Class-2
		Machine Model: Class-B

3. HARDWARE SPECIFICATION

3.1 Block Diagram and PIN Diagram

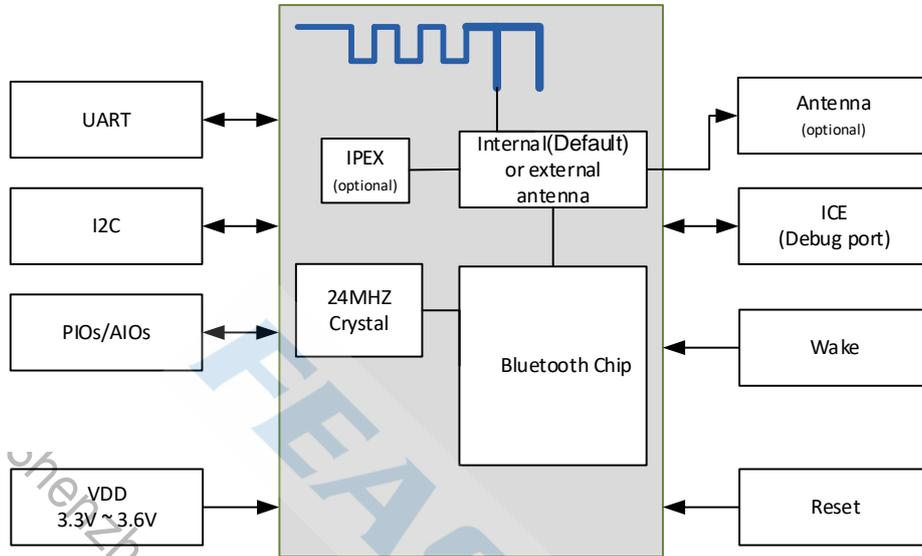


Figure 2: Block Diagram

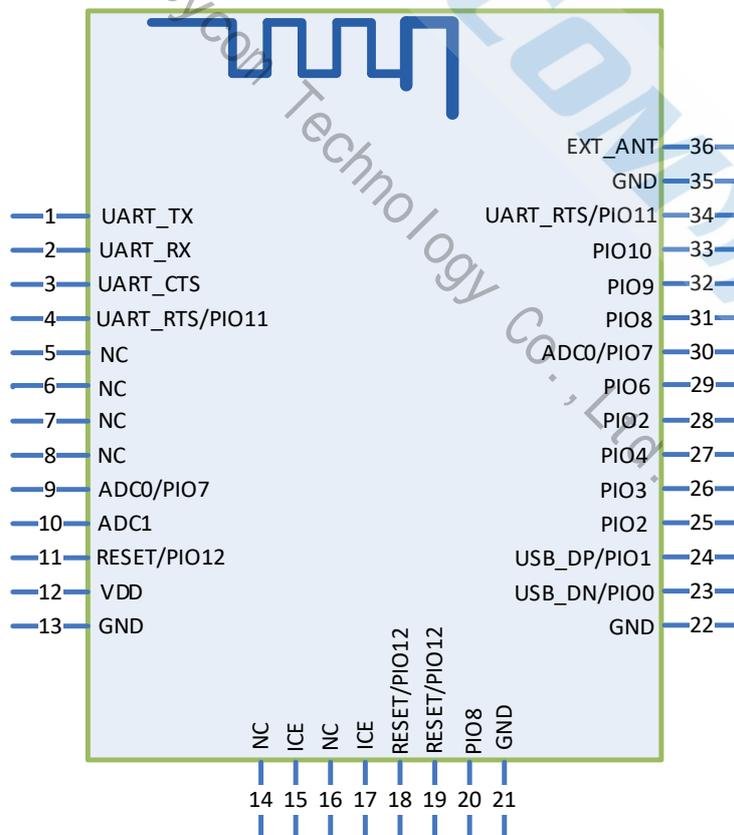


Figure 3: FSC-HC05 PIN Diagram(Top View)

3.2 PIN Definition Descriptions

Table 2: Pin definition

Pin	Pin Name	Type	Pin Descriptions	Notes
1	UART_TX	O	UART data output	Note 1
2	UART_RX	I	UART data input	Note 1
3	UART_CTS	I	UART clear to send active low Alternative Function: Programmable input/output line	Note 1
4,34	UART_RTS/PIO11	I/O	UART request to send active low Alternative Function: Programmable input/output line	Note 1
5	NC		NC	
6	NC		NC	
7	NC		NC	
8	NC		NC	
9,30	ADC0/PIO7	I/O	Analogue programmable I/O line Alternative Function: Programmable input/output line Alternative Function: I2C DATA line	Note 1,3
10	ADC1	I/O	Analogue programmable I/O line Alternative Function: Programmable input/output line	Note 1
11,18,19	RESET/PIO12	I/O	External reset input: Active LOW, with an inter an internal pull-up Set this pin low reset to initial state. Alternative Function: Programmable input/output line NC if not needed.	Note 1
12	VDD	Vdd	Power supply voltage 3.3V ~ 3.6V	
13	GND	Vss	Power Ground	
14	NC		NC	
15,17	ICE	I/O	Debug port, Tx & Rx	
16	NC		NC	
20,31	PIO8	I/O	Programmable input/output line Alternative Function: LED(Default)	Note 1
21	GND	Vss	Power Ground	
22	GND	Vss	Power Ground	
23	USB_DN/PIO0	I/O	USB port. Alternative Function: Programmable input/output line	Note 1
24	USB_DP/PIO1	I/O	USB port. Alternative Function: Programmable input/output line	Note 1
25,28	PIO2	I/O	Programmable input/output line	
26	PIO3	I/O	Programmable input/output line	
27	PIO4	I/O	Programmable input/output line	
29	PIO6	I/O	Programmable input/output line Alternative Function: I2C CLK line	Note 1,3
32	PIO9	I/O	Programmable input/output line Alternative Function: BT Status(Default)	Note 1,4
35	GND	Vss	RF Ground	

36	EXT_ANT	O	RF signal output	Note 5
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Module Pin Notes:

Note 1	For customized module, this pin can be work as I/O Interface.
Note 2	BT Status (Default)-- Disconnected: Low Level; Connected: High Level.
Note 3	I2C Serial Clock and Data. It is essential to remember that pull-up resistors on both SCL and SDA lines are not provided in the module and MUST be provided external to the module.
Note 4	LED(Default)-- Power On: Light Slow Shinning ; Connected: Steady Lighting.
Note 5	By default, this PIN is an empty feet. This PIN can connect to an external antenna to improve the Bluetooth signal coverage. If you need to use an external antenna, by modifying the module on the OR resistance to block out the on-board antenna; Or contact Feasycom for modification.

4. PHYSICAL INTERFACE

4.1 Power Supply

The transient response of the regulator is important. If the power rails of the module are supplied from an external voltage source, the transient response of any regulator used should be 20 μ s or less. It is essential that the power rail recovers quickly.

4.2 RF Interface

For this module, the default mode of the antenna is internal antenna.

The user can connect the 50 ohm antenna directly to the RF port.

- 2402–2480 MHz
- TX output power of +5dBm.
- Receiver to achieve maximum sensitivity -95dBm @ 0.1% SPP

4.3 Serial Interfaces

4.3.1 UART

FSC-HC05 provides one channels of Universal Asynchronous Receiver/Transmitters(UART)(Full-duplex asynchronous communications). The UART Controller performs a serial-to-parallel conversion on data received from the peripheral and a parallel-to-serial conversion on data transmitted from the CPU. Each UART Controller channel supports ten types of interrupts.

This is a standard UART interface for communicating with other serial devices. The UART interface provides a simple mechanism for communicating with other serial devices using the RS232 protocol.

When the module is connected to another digital device, UART_RX and UART_TX transfer data between the two devices.

This module output is at 3.3V CMOS logic levels (tracks VCC). Level conversion must be added to interface with an RS-232 level compliant interface.

Table 3: Possible UART Settings

Parameter	Possible Values	
Baudrate	Minimum	1200 baud ($\leq 2\%$ Error)
	Standard	115200bps($\leq 1\%$ Error)
	Maximum	921600bps($\leq 1\%$ Error)
Flow control	Supports Automatic Flow Control (CTS and RTS lines)	
Parity	None, Odd or Even	
Number of stop bits	1 / 1.5/2	
Bits per channel	5/6/7/8	

When connecting the module to a host, please make sure to follow .

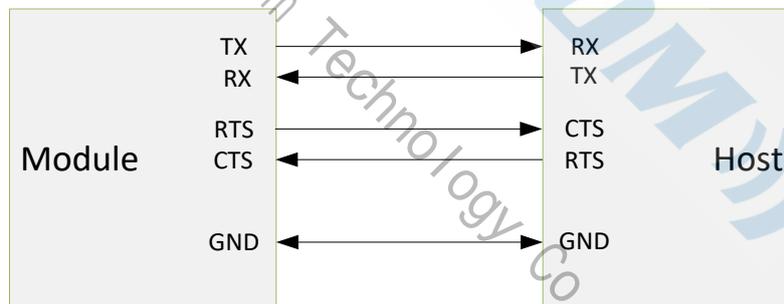


Figure 4: UART Connection

4.3.2 I2C Interface

I2C is a two-wire, bi-directional serial bus that provides a simple and efficient method of data exchange between devices. The I2C standard is a true multi-master bus including collision detection and arbitration that prevents data corruption if two or more masters attempt to control the bus simultaneously.

FSC-HC05 has I2C master which supports 100Kbps and 400Kbps.

Data is transferred between a Master and a Slave synchronously to SCL on the SDA line on a byte-by-byte basis. Each data byte is 8-bit long. There is one SCL clock pulse for each data bit with the MSB being transmitted first. An acknowledge bit follows each transferred byte. Each bit is sampled during the high period of SCL; therefore, the SDA line may be changed only during the low period of SCL and must be held stable during the high period of SCL. A transition on the SDA line while SCL is high is interpreted as a command (START or STOP). Please refer to the following figure for more details about I2C Bus Timing.

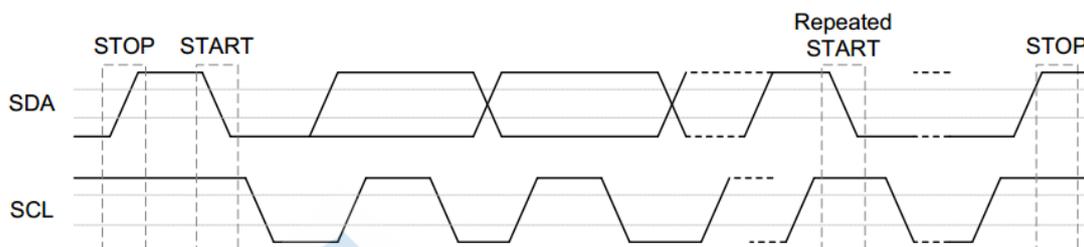


Figure 5: I2C Bus Timing

The device on-chip I2C logic provides the serial interface that meets the I2C bus standard mode specification. The I2C port handles byte transfers autonomously. The I2C H/W interfaces to the I2C bus via two pins: SDA and SCL. Pull up resistor is needed for I2C operation as these are open drain pins. When the I/O pins are used as I2C port, user must set the pins function to I2C in advance.

4.3.3 USB Device Controller

USB2.0 fullspeed, support host mode.

5. ELECTRICAL CHARACTERISTICS

5.1 Absolute Maximum Ratings

Absolute maximum ratings for supply voltage and voltages on digital and analogue pins of the module are listed below. Exceeding these values causes permanent damage.

The average PIO pin output current is defined as the average current value flowing through any one of the corresponding pins for a 100mS period. The total average PIO pin output current is defined as the average current value flowing through all of the corresponding pins for a 100mS period. The maximum output current is defined as the value of the peak current flowing through any one of the corresponding pins.

Table 4: Absolute Maximum Rating

Parameter	Min	Max	Unit
VDD_3V3 DC Power Supply	-0.3	+3.6	V
T _A - Operating Temperature	-20	+85	°C
T _{ST} - Storage Temperature	-20	+85	°C

5.2 Recommended Operating Conditions

Table 5: Recommended Operating Conditions

Parameter	Min	Type	Max	Unit
VDD_3V3 DC Power Supply	3.3	3.3	3.6	V
T _A - Operating Temperature	-20	25	+85	°C
T _{ST} - Storage Temperature	-20	25	+85	°C
V _{IH} High Level	VDD_3V3-0.3		VDD_3V3+0.3	V
V _{IL} Low Level	VSS		VSS+0.3	V
V _{OH} High Level	VDD_3V3-0.3		VDD_3V3+0.3	V
V _{OL} Low Level	VSS		VSS+0.3	V

5.3 RF characteristics

Table 6: Transmitter Characteristics

Parameter	Min	Type	Max	Unit
Operating Frequency	2400		2480	MHz
RF output power	-20	0	5	dBm

Table 7: SPP Receiver Characteristics

Parameter	Min	Type	Max	Unit
High Gain mode, Sensitivity @0.1%		-95		dBm
Standard Gain mode, Sensitivity @0.1%		-92		dBm
Maximum Input Power		0		dBm
Co-channel C/I, Basic Rate, GFSK		7		dB
ACS C/I 1MHz, Basic Rate, GFSK		5.5	7	dB
ACS C/I 2MHz, Basic Rate, GFSK		-36	-34	dB
ACS C/I 3MHz, Basic Rate, GFSK		-43		dB
ACS C/I Image channel, Basic Rate, GFSK		-34		dB
C/I 1 MHz adjacent to image channel, Basic Rate, GFSK		-28		dB

6. MSL & ESD

Table 8: MSL and ESD

Parameter	Value
MSL grade:	MSL 3
ESD grade:	Human Body Model: Class-2 Machine Model: Class-B

7. RECOMMENDED TEMPERATURE REFLOW PROFILE

Prior to any reflow, it is important to ensure the modules were packaged to prevent moisture absorption. New packages contain desiccant (to absorb moisture) and a humidity indicator card to display the level maintained during storage and shipment. If directed to bake units on the card, please check the below **next table** and follow instructions specified by IPC/JEDEC J-STD-033.

Note: The shipping tray cannot be heated above 65°C. If baking is required at the higher temperatures displayed in the below **next table**, the modules must be removed from the shipping tray.

Any modules not manufactured before exceeding their floor life should be re-packaged with fresh desiccant and a new humidity indicator card. Floor life for MSL (Moisture Sensitivity Level) 3 devices is 168 hours in ambient environment 30°C/60%RH.

Table 9: Recommended baking times and temperatures

MSL	125°C Baking Temp.		90°C/≤ 5%RH Baking Temp.		40°C/ ≤ 5%RH Baking Temp.	
	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%	Saturated @ 30°C/85%	Floor Life Limit + 72 hours @ 30°C/60%
3	9 hours	7 hours	33 hours	23 hours	13 days	9 days

Feasycom surface mount modules are designed to be easily manufactured, including reflow soldering to a PCB. Ultimately it is the responsibility of the customer to choose the appropriate solder paste and to ensure oven temperatures during reflow meet the requirements of the solder paste. Feasycom surface mount modules conform to J-STD-020D1 standards for reflow temperatures.

The soldering profile depends on various parameters necessitating a set up for each application. The data here is given only for guidance on solder reflow.

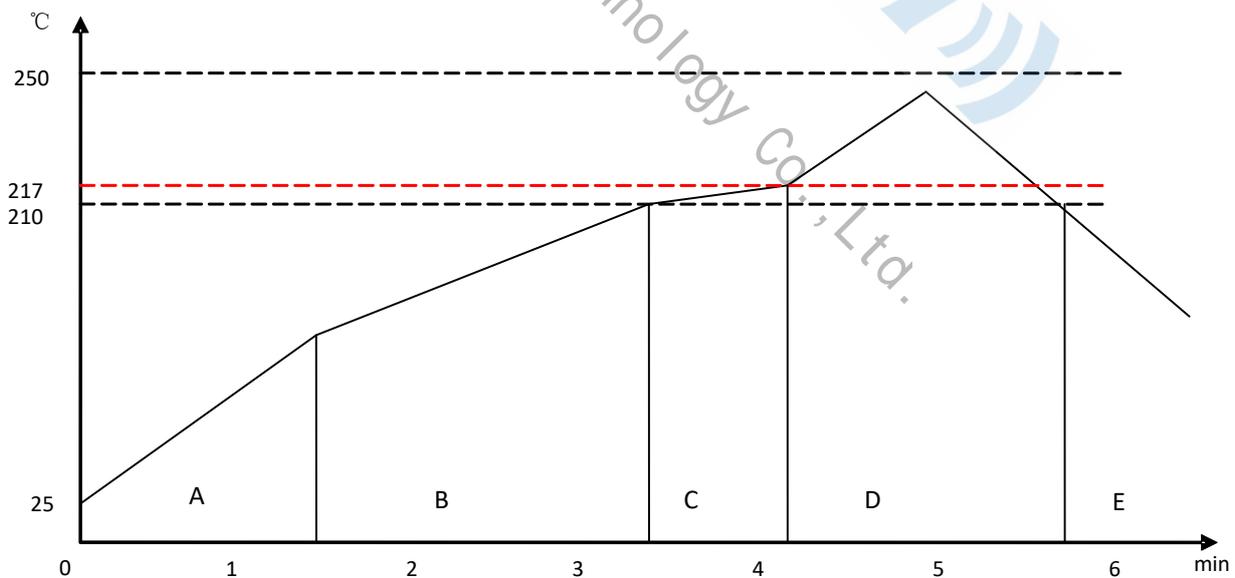


Figure 6: Typical Lead-free Re-flow

Pre-heat zone (A) — This zone raises the temperature at a controlled rate, **typically 0.5 – 2 °C/s**. The purpose of this zone is to preheat the PCB board and components to 120 ~ 150 °C. This stage is required to distribute the heat uniformly to the PCB board and completely remove solvent to reduce the heat shock to components.

Equilibrium Zone 1 (B) — In this stage the flux becomes soft and uniformly encapsulates solder particles and spread over PCB board, preventing them from being re-oxidized. Also with elevation of temperature and liquefaction of flux, each activator and rosin get activated and start eliminating oxide film formed on the surface of each solder particle and PCB board. **The temperature is recommended to be 150° to 210° for 60 to 120 second for this zone.**

Equilibrium Zone 2 (C) (optional) — In order to resolve the upright component issue, it is recommended to keep the temperature in 210 – 217 ° for about 20 to 30 second.

Reflow Zone (D) — The profile in the figure is designed for Sn/Ag3.0/Cu0.5. It can be a reference for other lead-free solder. The peak temperature should be high enough to achieve good wetting but not so high as to cause component discoloration or damage. Excessive soldering time can lead to intermetallic growth which can result in a brittle joint. The recommended peak temperature (Tp) is 230 ~ 250 °C. The soldering time should be 30 to 90 second when the temperature is above 217 °C.

Cooling Zone (E) — The cooling rate should be fast, to keep the solder grains small which will give a longer-lasting joint. **Typical cooling rate should be 4 °C.**

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8. MECHANICAL DETAILS

8.1 Mechanical Details

- Dimension: 13mm(W) x 26.9mm(L) x 2.0mm(H) Tolerance: $\pm 0.1\text{mm}$
- Module size: 13mm X 26.9mm Tolerance: $\pm 0.2\text{mm}$
- Pad size: 1mmX0.8mm Tolerance: $\pm 0.2\text{mm}$
- Pad pitch: 1.5mm Tolerance: $\pm 0.1\text{mm}$

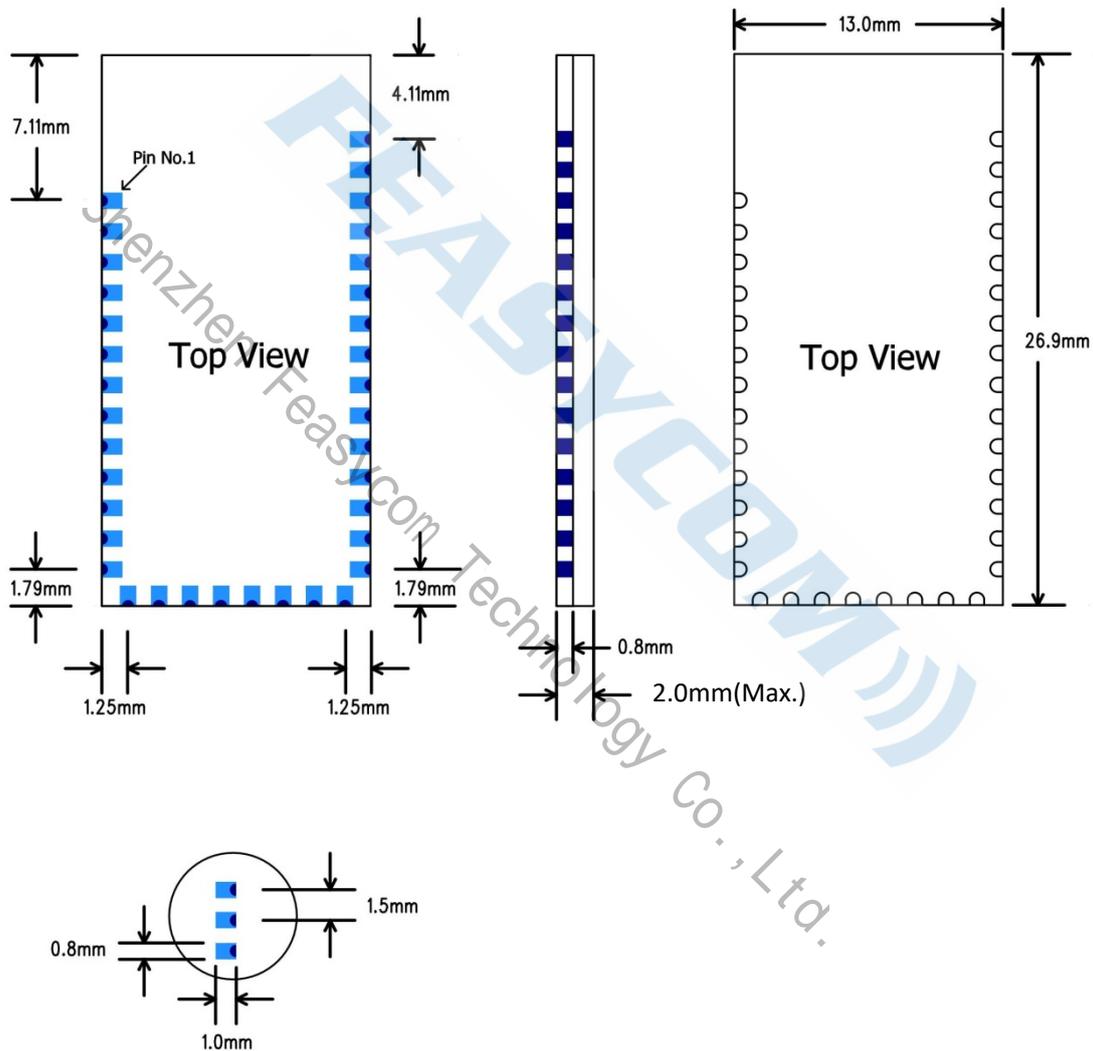


Figure 7: FSC-HC05 footprint

8.2 Host PCB Land Pattern and Antenna Keep-out for FSC-HC05

Please check the picture below for Pad Structure and Keep Out Area:

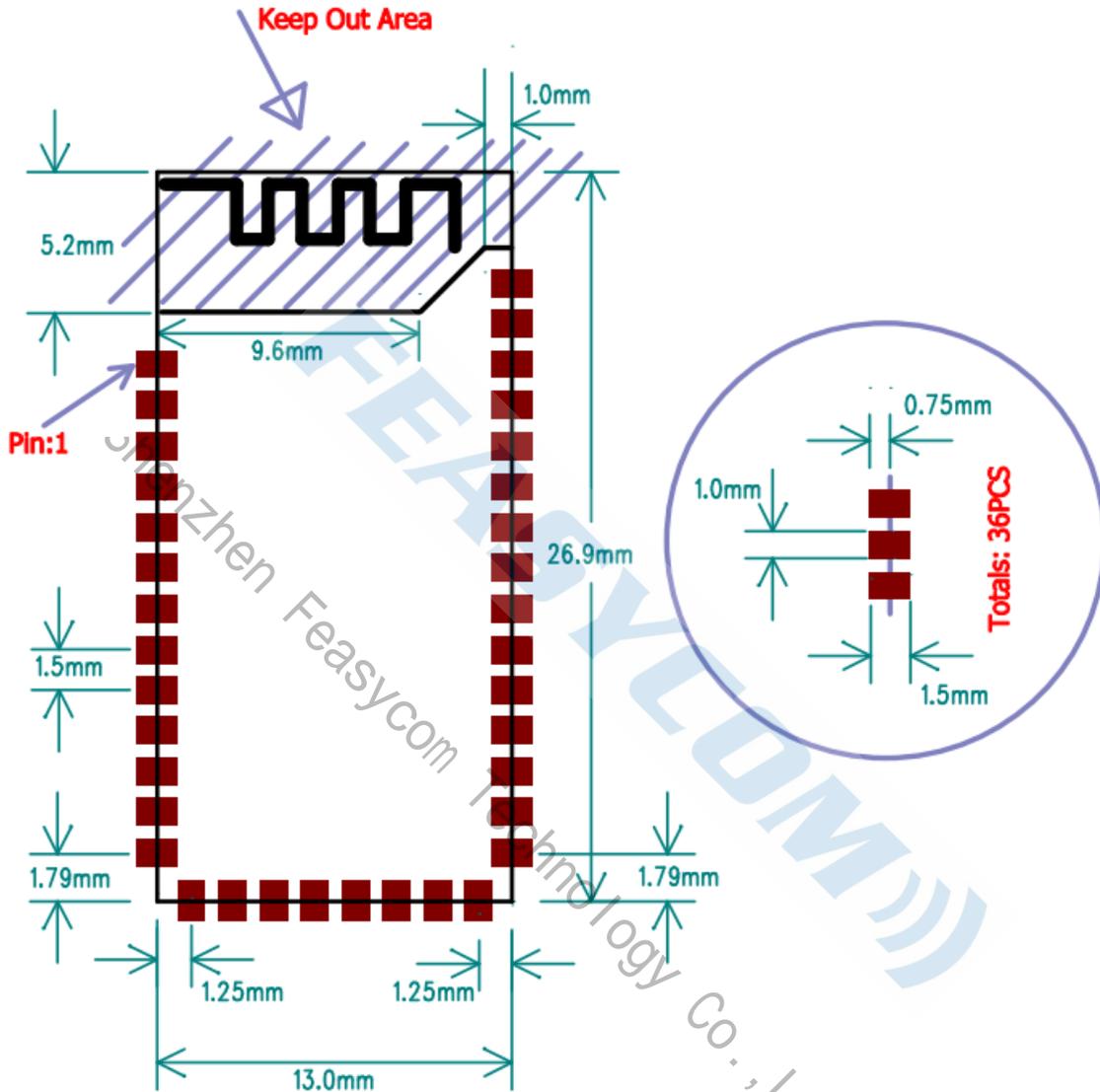


Figure 8: Host PCB-Top View

9. HARDWARE INTEGRATION SUGGESTIONS

9.1 Soldering Recommendations

FSC-HC05 is compatible with industrial standard reflow profile for Pb-free solders. The reflow profile used is dependent on the thermal mass of the entire populated PCB, heat transfer efficiency of the oven and particular type of solder paste used. Consult the datasheet of particular solder paste for profile configurations.

Feasycom will give following recommendations for soldering the module to ensure reliable solder joint and operation of the module after soldering. Since the profile used is process and layout dependent, the optimum profile should be studied case by case. Thus following recommendation should be taken as a starting point guide.

9.2 Layout Guidelines(Internal Antenna)

It is strongly recommended to use good layout practices to ensure proper operation of the module. Placing copper or any metal near antenna deteriorates its operation by having effect on the matching properties. Metal shield around the antenna will prevent the radiation and thus metal case should not be used with the module. Use grounding vias separated max 3 mm apart at the edge of grounding areas to prevent RF penetrating inside the PCB and causing an unintentional resonator. Use GND vias all around the PCB edges.

The mother board should have no bare conductors or vias in this restricted area, because it is not covered by stop mask print. Also no copper (planes, traces or vias) are allowed in this area, because of mismatching the on-board antenna.

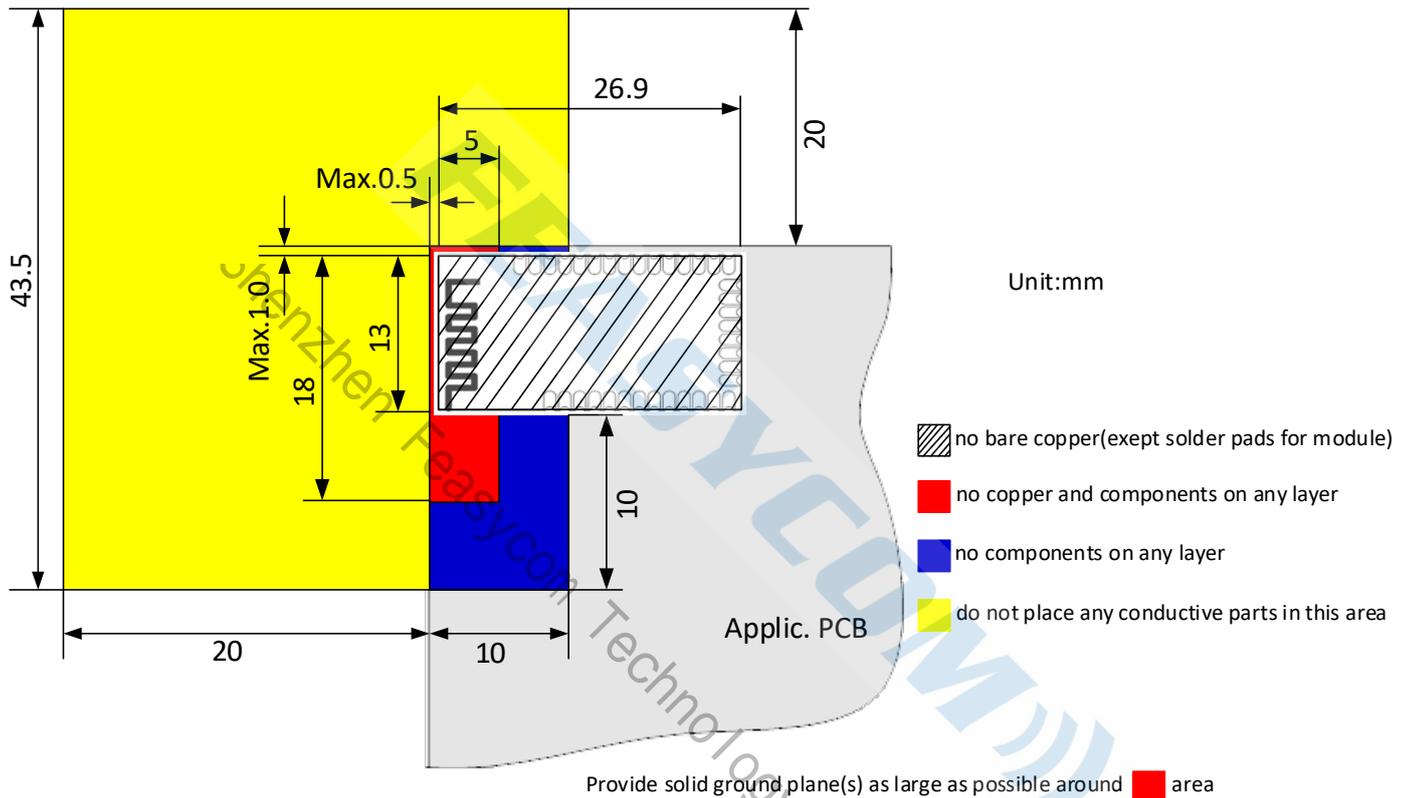


Figure 9: FSC-HC05 Restricted Area

Following recommendations helps to avoid EMC problems arising in the design. Note that each design is unique and the following list do not consider all basic design rules such as avoiding capacitive coupling between signal lines. Following list is aimed to avoid EMC problems caused by RF part of the module. Use good consideration to avoid problems arising from digital signals in the design.

Ensure that signal lines have return paths as short as possible. For example if a signal goes to an inner layer through a via, always use ground vias around it. Locate them tightly and symmetrically around the signal vias. Routing of any sensitive signals should be done in the inner layers of the PCB. Sensitive traces should have a ground area above and under the line. If this is not possible, make sure that the return path is short by other means (for example using a ground line next to the signal line).

9.3 Layout Guidelines(External Antenna)

Placement and PCB layout are critical to optimize the performances of a module without on-board antenna designs. The trace from the antenna port of the module to an external antenna should be 50Ω and must be as short as possible to avoid any interference into the transceiver of the module. The location of the external antenna and RF-IN port of the module should be kept away from any noise sources and digital traces. A matching network might be needed in between the external antenna and RF-IN port to better match the impedance to minimize the return loss.

As indicated in below, RF critical circuits of the module should be clearly separated from any digital circuits on the system board. All RF circuits in the module are close to the antenna port. The module, then, should be placed in this way that module digital part towards your digital section of the system PCB.

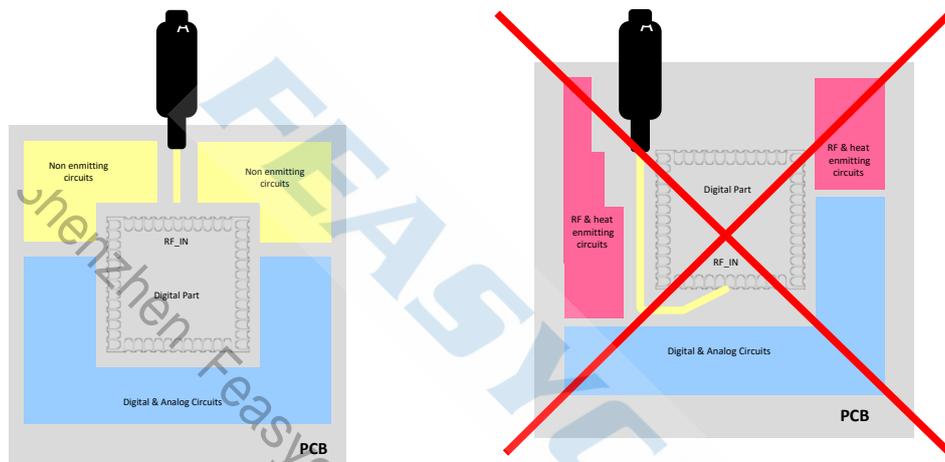


Figure 10: Placement the Module on a System Board

9.3.1 Antenna Connection and Grounding Plane Design

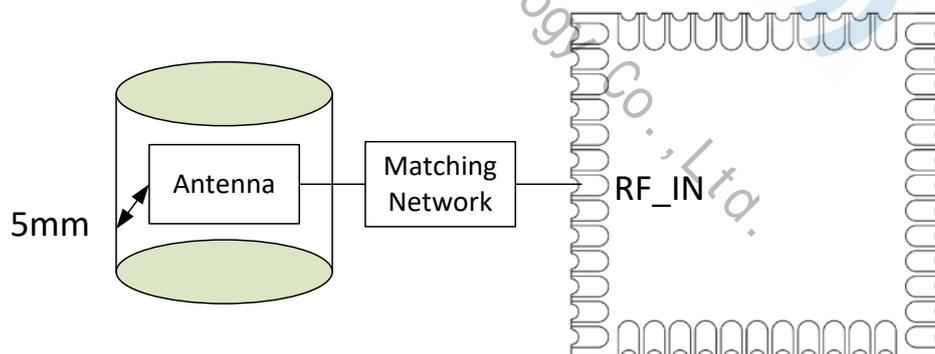


Figure 11: Leave 5mm Clearance Space from the Antenna

General design recommendations are:

- The length of the trace or connection line should be kept as short as possible.
- Distance between connection and ground area on the top layer should at least be as large as the dielectric thickness.
- Routing the RF close to digital sections of the system board should be avoided.

- To reduce signal reflections, sharp angles in the routing of the micro strip line should be avoided. Chamfers or fillets are preferred for rectangular routing; 45-degree routing is preferred over Manhattan style 90-degree routing.

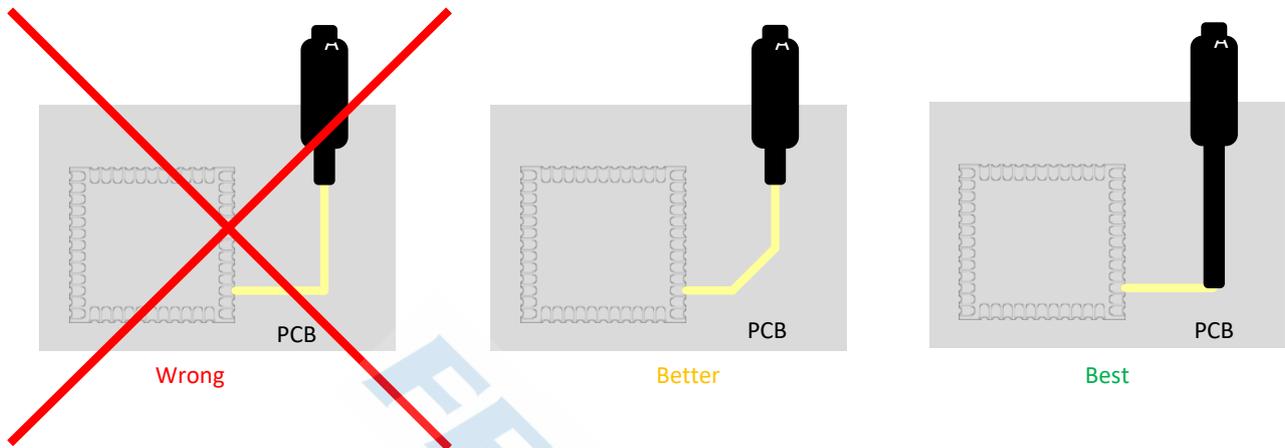


Figure 12: Recommended Trace Connects Antenna and the Module

- Routing of the RF-connection underneath the module should be avoided. The distance of the micro strip line to the ground plane on the bottom side of the receiver is very small and has huge tolerances. Therefore, the impedance of this part of the trace cannot be controlled.
- Use as many vias as possible to connect the ground planes.

10. PRODUCT PACKAGING INFORMATION

10.1 Default Packing

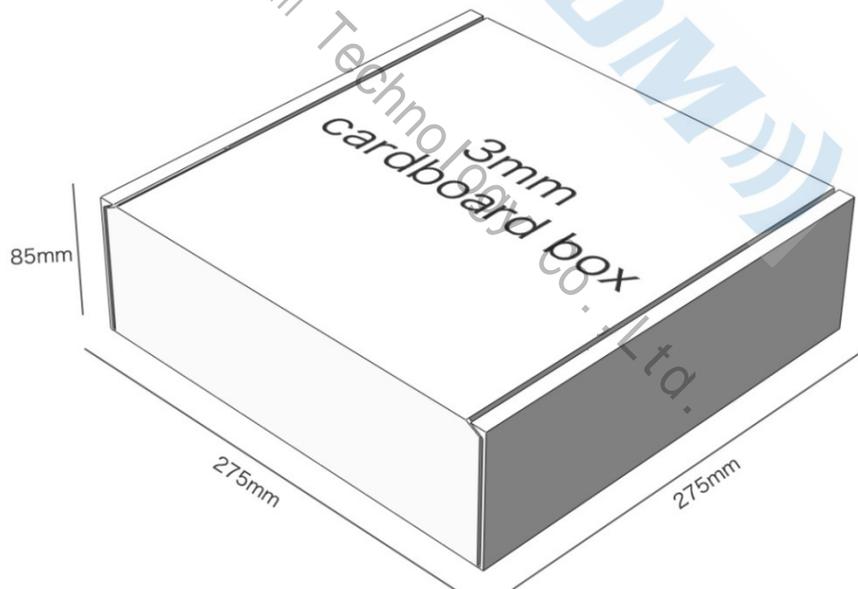
- Tray vacuum
- Tray Dimension: 180mm * 195mm





Figure 13: Tray vacuum

10.2 Packing box(For reference only)



* If require any other packing, must be confirmed with customer

* Package: 1000PCS Per Carton (Min Carton Package)

Figure 14: Packing Box

11. APPLICATION SCHEMATIC

